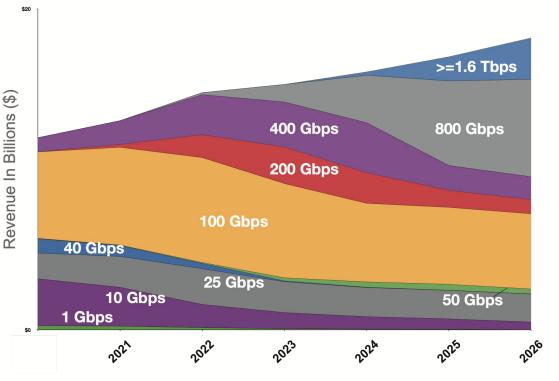


Rise of the Merchant Silicon

Next gen ASICs for the peering fabric

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Ethernet Switch Revenue Forecast



Source: Dell'Oro March 2022 - Long Term Ethernet Switch Forecast

800G and 1600G expected to be 45% of Market in 2026

400G and below expected to be 55% of Market in 2026

ARISTA

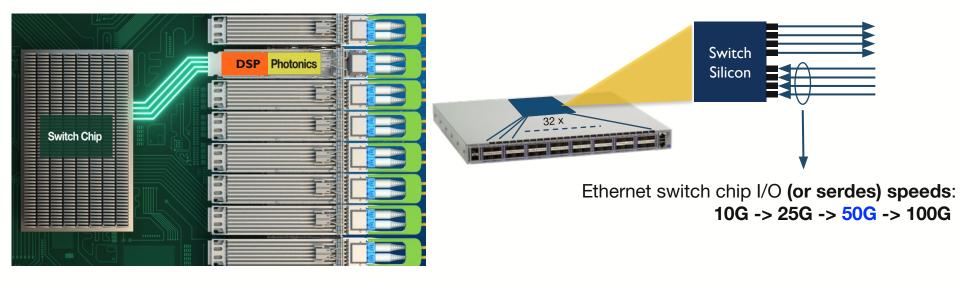
Single-chip Switch Bandwidth & Serdes Speeds



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SERDES Speeds are Key to Scaling networks

- Serdes (or Serializer-Deserializers) refer to the technology used for high-speed chip I/O
- Serdes speeds place a fundamental limit on datacenter bandwidth
- The easiest way to go faster is (for serdes speeds) to go Faster



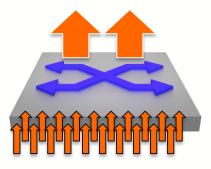


"The easiest way to go faster is to go faster"



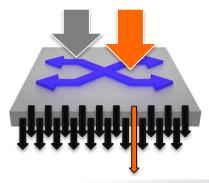


When Buffers Matter in Networks



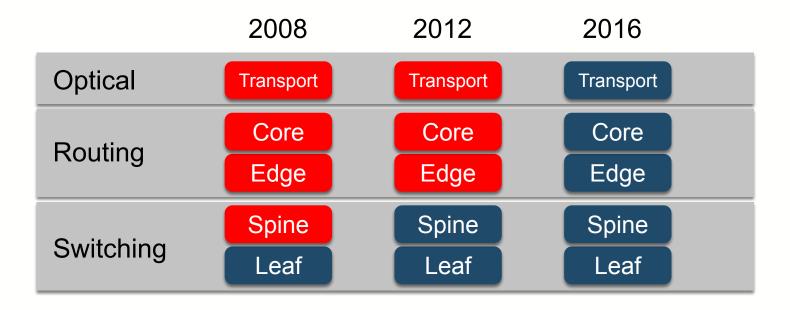
Incast (Many to Fewer)

Speed Change (Faster to Slower)





The Evolution of Merchant Silicon



Proprietary Chips Merchant Silicon



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Process Technology Improvements (TSMC)

| Process Node | 7nm | 5nm | 3nm |
|----------------------|------|------|------|
| Relative Density | 1 | 1.5 | 2.25 |
| Speed @ IsoPower | 1 | 1.15 | 1.4 |
| Power @ IsoSpeed | 1 | 0.8 | 0.6 |
| Volume Manufacturing | 2019 | 2021 | 2023 |

Each process generation enables more throughput, better Power Efficiency, more buffers, bigger routing tables, etc



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Cost of silicon design

Cost of design (aka tape out) has risen significantly

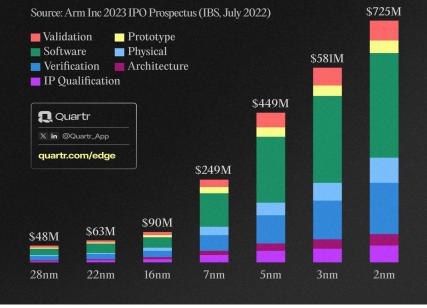
- 28nm: 48M\$
- 22nm: 63M\$ +33%
- 16nm: 90M\$ +43%
- 7nm: 249M\$ +176%
- 5nm: 449M\$ +80%
- 3nm: 581M\$ +30%
- 2nm: 725M\$ +25% (new: ~ 2nd half of 2025)

This favors merchant silicon because of higher volume

This also leads to:

- Lower cost / better economy of scale
- Faster product cycles
- Faster innovation (because of shorter cycles)
- Lower power consumption
- Better scale
- More features (not always but often)

Cost of Chip Design by Nanometer





Choices in Switching Silicon

All chip makers have access to the same technology

- same fabs and processes
- same memories, TCAMs, serdes
- same clock rate

Differences arise primarily because of

- design tradeoffs for different use cases
- process shifts (28nm -> 16nm -> 7nm -> 5nm)
- faster innovation cycles

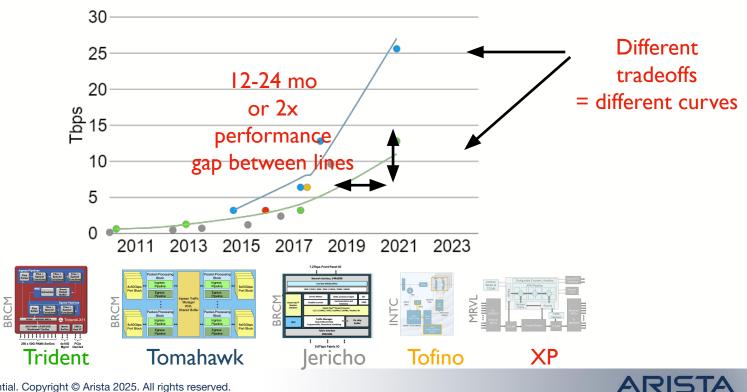


There is <u>no</u> fundamental advantage to proprietary silicon



Merchant Silicon Trajectory

10 years at Arista, across chip families



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2024: Next Generation Silicon for Networks









Tofino

- very high density
- very high performance
- very low power per Gbps
- Highly flexible and programmable
- intermediate programming complexity
- deterministic, low latency

Tomahawk5

- 2x higher performance
- Up to 51.2 Tbps
 - 165MB Buffer
- Scale Out & High Radix

Trident4

- 4x higher performance
- Up to 12.8 Tbps
- 132MB Buffer
- Programmable Pipeline

Jericho2C+

- 50% higher performance
- 7.2 Tbps
- 2.7 Bpps
- Deep Buffers
- Extensible



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The last Tofino?

McKeown, Nick

Jan 30, 2023, 4:02:49 AM 🟠 🗰 :

Dear P4 Community

Since its introduction a decade ago, P4 has led to a Cambrian explosion of ideas including new protocols, new applications like in-band telemetry; and new testing, validation, and formal verification techniques. P4 has become the industry standard for programming and specifying forwarding behavior. As a measure of success, one in four papers published at ACM SIGCOMM 22 – the top contenence for networking research – are blue to P4 in some way.

A you may know, Intel resently announced that it will sing development of the next-generation Intel® Tofno® Untel®pert FahicP Processo (IPP) products currently on its roadmaps Newsex; we will continue to sail and approach or avoising fahicProproducts. Intel Tofno® IPP proved to the vori of hardy noce a hold will programmable switches without compromising on performance. Tofno's program independent switch architecture (IPSA) will have a lasting effect on how packet-processing pipelines are built; if has already influenced programmable products at the degree sub as a smittle can def UP.

Although Tofino's roadmap is curtailed, I'd like to make clear that the team here at Intel remains committed to P4 as the language of choice across a wide range of Intel products and platforms, including our IPUs (ASIC and FPGA). The mission of Intel Network and Edge (NEX) group remains unchanged: we design and sell products to enable network owners to decide how packets are processed and to deploy their own creative new solutions. P lia an essential part of our ordima for IPUs (ASIC PGAs, DPC), DPC, MC, and more

Intel remains committed to open source and we continue to contribute to, and support, the P4 community, including the design of the P4 language, standard architectures, control APIs, and applications. And we will continue to develop open-source targets like P4TC, which integrates P4 into the Linux kernel, bringing a new level of programmability to the network edge.

Together, as a community, we can feel proud for successfully fostering a "revolution" in how industry and researchers think about networks. In the past, behaviors were baked into fixed function hardware; today, we can specify and program behaviors in software that are compiled and deployed in-situ, allowing beautiful new ideas to be tested and deployed more quick). There is no going back.

P4 got its start when a small group got together to think about new abstractions for programmable networking. We've now grown into a vibrant community of researchers and practitioners who are pushing the boundaries of what's possible across the full range of programmable targets. I'm honored to be a part of this community and I'm inspired by what we've accompliabed and excited about what we will calieve in the future.

Nick McKeown Senior VP & GM, Senior Fellow Network and Edge Group (NEX Intel.

"As you may know, Intel recently announced that it will stop development of the next-generation Intel® Tofino® Intelligent Fabric Processor (IFP) products currently on its roadmap."

Public announcement by Nick McKeown (Intel Senior VP & GM) https://groups.google.com/a/lists.p4.org/g/p4-announce/c/frXi_jjmawE





2024: Next Generation Silicon for Networks









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- Up to 51.2 Tbps
 - 165MB Buffer
- Scale Out & High Radix

Trident4

- 4x higher performance
- Up to 12.8 Tbps
- 132MB Buffer
- Programmable Pipeline

Jericho2C+

- 50% higher performance
- 7.2 Tbps
- 2.7 Bpps
- Deep Buffers
- Extensible





Tomahawk

Tomahawk5 for AI Networks

- 2X performance
 - 51.2Tbps: 512 x 100G PAM4
 - Powerful new SerDes help in supporting LPO optics
- Efficient and Scalable Architecture
 - IPv4/v6, VxLAN and advanced instrumentation
- High Radix with flexible port speeds
 - Up to 320 front panel ports at 10G to 800G speeds
- Cloud optimized pipeline and unified packet buffer
 - 165MB shared buffer
 - Absorbs bursts 10x better

| Tomahawk5 | | | | | | |
|-----------------------------------|---|--|--|--|--|--|
| Scheduler | Shared Packet Buffer | | | | | |
| | Packet Processing (L2/L3, IPv4/IPv6, MPLS) | | | | | |
| VLAN, Ingress, Egre | ess Field Processors | | | | | |
| Smart Hash Load Balance Engine | Advanced Instrumentation | | | | | |
| 512 x 100G PAM4 SerDes | | | | | | |
| | | | | | | |



Tomahawk Evolution

| | 7060X4 12.8T (TH3) | 7060X5 25.6 (TH4) | 7060X6 51.2 (TH5) | |
|----------------------|------------------------|--|----------------------|--------------------------------|
| Max I/O | 256 x 50G 32 x 400G | 512 x 50G 64 x 800G 512 x 50G 128 x 400G 64 x 400G 256 x 200G 512 x 100G 512 x 100G | | 2X I/O Increase |
| Max Throughput | 12.8Tbps | 25.6Tbps | 51.2Tbps | |
| Logical Ports | 144 | 256 | 320 | |
| Buffer | 64MB | 114MB | 165MB | Increased Buffer |
| L2 MAC | 8K | 12 | Consistent Scale | |
| L3 Hosts | 8К | Shared w | /ith ALPM | Consistent Scale |
| IPv4/IPv6 LPM (ALPM) | | | | |
| Tunnel TCAM | 2 | 56 | 512 | |
| True Egress Mirror | No | | Yes | Advanced Traffic Management |
| VXLAN | Not Supported Yes | | Yes | |
| LPO Support | Not Supported | Not Supported | Yes | |

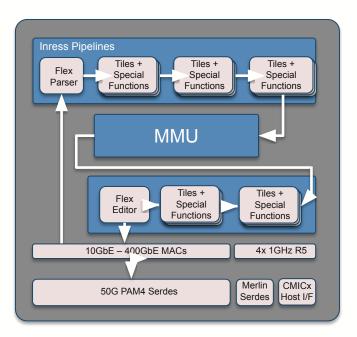




Trident

Arista 7050X4 X.11(12.8T) vs X.9(8.0T) – Comparison

| | 7050X3 3.2T (TD3) | 7050X4 12.8T (TD4) | 7050X4 8T (TD4) |
|---|-----------------------------|------------------------------|---------------------------|
| Max I/O | 128 x 25G 32 x 100G | 256 x 50G 32 x 400G | 160 x 50G 20 x 400G |
| Max Throughput | 3.2Tbps | 12.8Tbps | 8.0Tbps |
| Logical Ports | 128 | 144 | 72 |
| Buffer | 32MB | 132MB (Hybrid- Shared) | 82MB (Fully Shared) |
| Latency | 800ns | 900ns | |
| L2 MAC | 288K | 128K | |
| L3 Hosts | 168K | 320K | |
| IPv4/IPv6 LPM (ALPM) | 384K/192K | 800K/500K | |
| MACsec & IPSec | No | No | Yes (4.8T) |
| Exact Match Rules | 128K | 256K* | |
| Counters | 114K | 256K | |
| ACLs | 7K | 11K + 2K egress | |
| VXLAN, uRPF, VLAN Translation bit wide entries | Yes | Yes | |





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Consistent features

Advanced Instrumentation – In-band telemetry for latency monitoring

Dynamic Load Balancing – Traffic awareness improves ECMP performance

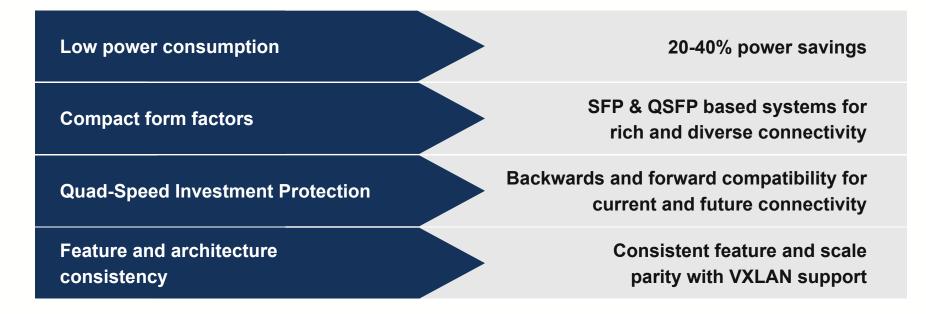
Traffic Scheduling – Microburst and Elephant Flow Detection and Prioritization

High-Performance Shared-Buffer memory – Improves burst absorption

Increased Routing and ACLs – Larger IPv4/v6 Scale and robustness



Trident4: Efficient System Design



Complete Portfolio - Uncompromised Features and Scale

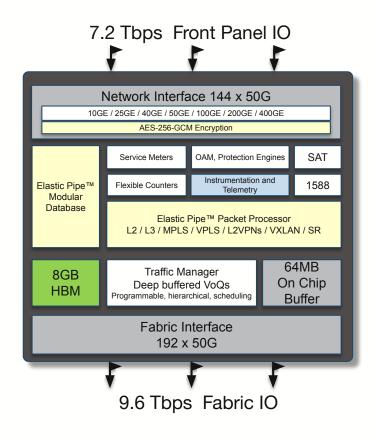




Jericho

16.8 Tbps - Jericho2C+

- 16.8 Tbps of High Performance with rich features
 - Total of 336 PAM-4 50G SerDes
 - 7.2Tbps Network I/O and 2.7Bpps packet processing
 - Flexible Network Interfaces 10G to 400G
 - Integrated TunnelSec Encryption (MACsec, IPsec, VXLANsec)
- Flexible Lookup Tables and Programmable Pipeline
 - Fungible on chip tables allow multiple use case profiles
 - Off-chip expandability with External table expansion (KBP)
 - Flexible Pipeline allows reconfiguration of forwarding
- Hierarchical Traffic Management with Deep Buffer
 - 8GB High Bandwidth Memory (HBM)
 - 64MB On Chip Buffer
- Network Instrumentation and Telemetry
 - Hardware Accelerator
 - Monitor of large numbers of sessions





Consistent System Resources: J2C+/J2/J2C/Q2C

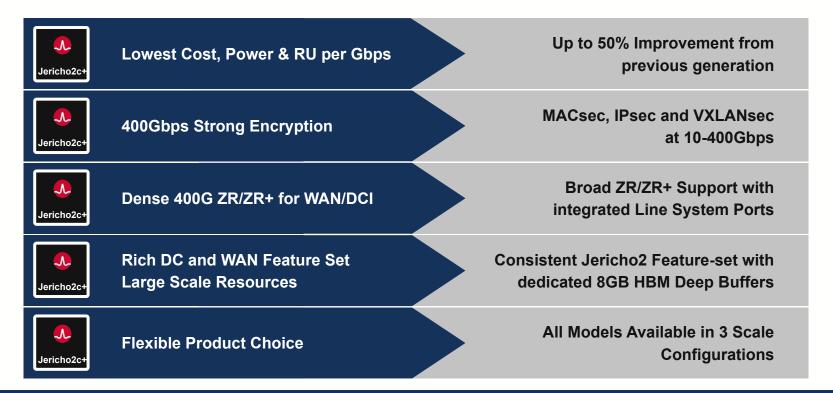
| | R3 Series | | R3K Series | | | |
|--|--------------|----------|-----------------|----------|------------|-------------|
| Profile | L3 (default) | Balanced | L3-XL (default) | L3-XXL | L3-XXXL | Balanced-XL |
| ARP Entries | 88k | 80k | 112k | 112k | 80k | 96k |
| MAC Addresses | 224k | 224k | 256k | 192k | 384k | 256k |
| IPv4 Unicast Routes | 1450k | 800k | 2250k | 2850k | 3950k | 1850k |
| Additional IPv4 Unicast Routes with FlexRoute | +1,792k | +1,792k | +2,048k | +1,536k | +3,072k | +2,048k |
| IPv6 Unicast Routes | 433-483k | 250-267k | 683-750k | 833-950k | 1100-1317k | 567-617k |
| Multicast Routes | 128k | 128k | 128k | 128k | 128k | 128k |
| TCAM ACL Entries (Per chip) | 24k | 24k | 24k | 24k | 24k | 24k |
| Traffic Policy ACL IPv4 Prefixes | 30k | 30k | 430k | 296k | 30k | 430k |
| Traffic Policy ACL IPv6 Prefixes | 10k | 10k | 150k | 100k | 10k | 150k |
| ECMP | 512-Way | 512-Way | 512-Way | 512-Way | 512-Way | 512-Way |

Maximum values dependent on shared resources / user configuration

Jericho2 hardware resources are fungible. Values shown are unidimensional maxima for default profiles



Jericho2C+ - The Engine for 400Gbps



Complete Portfolio - Uncompromised Features and Scale



Jericho based Portfolio

| | R Series | R2 Series | R3 Series | R3A Series | R4 Series |
|--------|-------------------------------|---|-------------------------------------|----------------------------|--|
| 25-35T | | | | 16.8T | 28.8T 144x106G PAM4 50GE - 800G Jericho3 |
| 15-25T | | Flex Route | | PAM4 Jericho2C+ - 400GE | 800 GbE |
| 5-15T | 25G SerDes | Jericho+ 1.8T 72x25G NRZ 1GE - 1000E | Jericho2 PAM4 10GE 50G SerDes | AES-256-GCM TunnelSec | |
| ≤2T | Jericho NRZ 1GE - 100GE | | Modular DB | | |
| | 2016-17 | 2018-19 | 2020-21 | 2022-23 | Future |

ARISTA



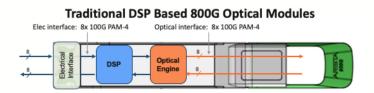
Rate Adapting 1G optics

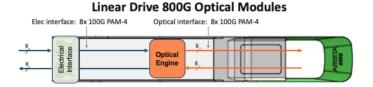
- Support 1G-LX and 1G-SX on platforms that have a minimum port speed of 10G
 - e.g. J2 based platforms have a minimum port speed of 10G
- Connect to other devices that use CL37 (optical) autoneg when the used platform does NOT support CL37 autoneg
 - some platforms support 1/10/25G but don't support CL37 autoneg



What are Linear Drive Optics Modules?

- 1. Linear Drive means no DSP or CDR in transceiver Just a linear driver to provide required modulator voltage
- 2. Requires a high-performance switch SERDES And very careful signal integrity design
- Achieves power savings similar to direct drive CPO While retaining the many advantages of pluggable optics modules Opportunity to cut optics module power by 50% and system power by up to 25%







How is AI transforming the service provider market?

- AI networks need VoQ based deep buffer fabrics
- Perfect fit for Jericho chips
- next version (J3) already in
- made for high amount of 800G interfaces
- also beneficial for SPs as BW demands still >>
- also SPs benefit from enhanced telemetry functions



Summary

Tomahawk

- Low latency
- Shallow Buffers
- High
 bandwidth
- Limited features

Trident

- Low latency
- Shallow Buffers
- Datacenter feature set
- Optimal in compute leaf/spine

Jericho

- Deep Buffer
- MPLS capable
- Hairpinning
- Optimal for arbitrary topologies





Thank You

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